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***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

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***PATENT***

In re application of: CATABAY et al.

Attorney Docket No.:

01-471/1D / LSIIP172D1

Application No.: 10/772,133

Examiner: NGUYEN, Tuan H.

Filed: February 3, 2004

Group: 2813

Title: MULTI-STEP PROCESS FOR FORMING  
A BARRIER FILM FOR USE IN COPPER LAYER  
FORMATION

Confirmation No.: 4269

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**AMENDMENT C**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This Amendment is in response to the Non-Final Office Action dated October 18, 2006. The Applicants thank the Examiner for his review and examination of this application during prosecution. It is respectfully requested that the above-referenced patent application be reconsidered in light of the amendments and comments made hereinbelow.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 8 of this paper.